



WANSEMI
万芯半导体

WP8205T

Enhancement Mode N-Channel Power MOSFET

TSSOP8/NMOS/20V/ ± 12 V/0.7V/6A/21m Ω

Rev1.4

20V, 21mΩ, 6A, N-Channel Enhancement Mode Power MOSFET

1.Features

- ◆ High Power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface Mount Package

V _{DS} Typ.	R _{DS(on)} Typ.	I _D Max.
20V	21mΩ @ 4.5V	6A
	25mΩ @ 2.5V	

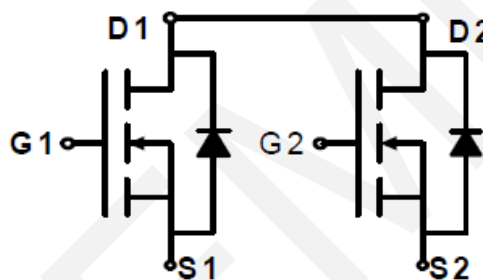
2.Applications

- ◆ Battery Protection
- ◆ Battery Powered Systems
- ◆ Power Management in Notebook Computer
- ◆ Portable Equipment



TSSOP8

Pin Description



Schematic Diagram

3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP8205T	8205A	TSSOP8	5,000	80,000

4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V _{DSS}	20	V
Gate to Source Voltage	V _{GSS}	±12	V
Drain Current-Continuous	I _D	6	A
Drain Current (Pulse)	I _{DM}	16	A
Maximum Power Dissipation	P _D	1.6	W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

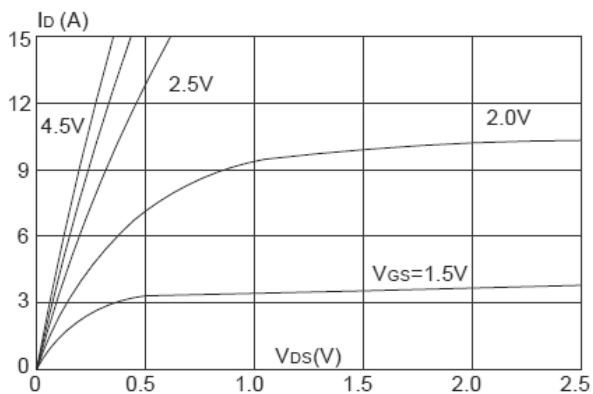
Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5. Electrical Characteristics at Ta=25°C (Note 2)

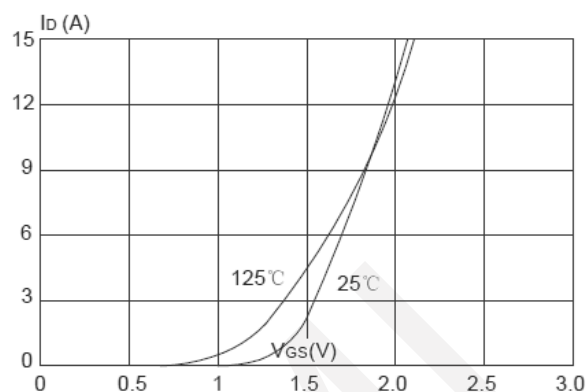
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu A, V_{GS} = 0V$	20	21	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{DS} = 250\mu A$	0.5	0.7	1.2	V
Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 6A, V_{GS} = 4.5V$	-	21	25	m Ω
		$I_D = 2A, V_{GS} = 2.5V$	-	25	32	m Ω
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 10V,$ Frequency = 1.0MHz	-	358	-	pF
Output Capacitance	C_{oss}		-	69	-	pF
Reverse Transfer Capacitance	C_{rss}		-	59	-	pF
Turn-ON Delay Time	$t_{d(on)}$	$V_{DD} = 10V, I_D = 6A,$ $V_{GS} = 4.5V,$ $R_{GEN} = 3\Omega$	-	16	-	ns
Turn-ON Rise Time	t_r		-	51	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	21	-	ns
Turn-ON Fall Time	t_f		-	19	-	ns
Total Gate Charge	Q_g	$V_{DS} = 10V,$ $V_{GS} = 4.5V,$ $I_D = 3A$	-	5.6	-	nC
Gate-Source Charge	Q_{gs}		-	0.8	-	nC
Gate-Drain Charge	Q_{gd}		-	1	-	nC
Diode Forward Voltage	V_{SD}	$I_D = 6A, V_{GS} = 0V$	-	0.9	1.2	V

Note 2: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

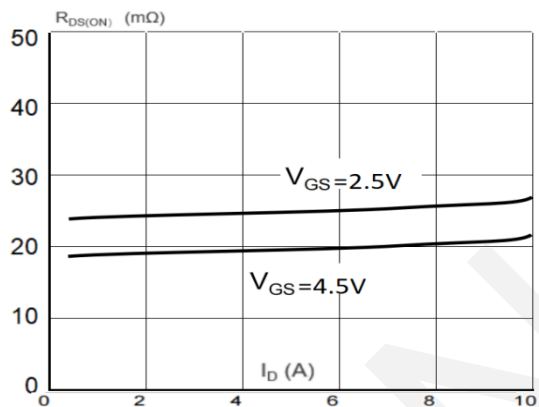
6. Typical electrical and thermal characteristics



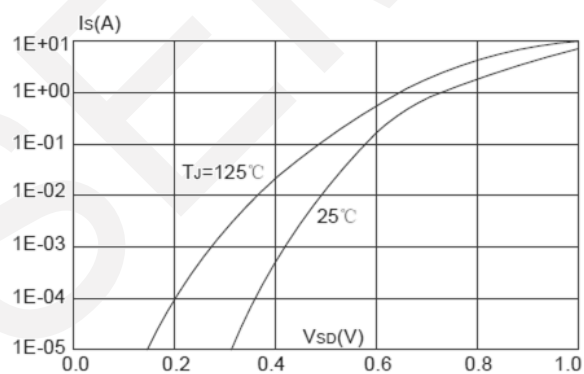
Output Characteristics



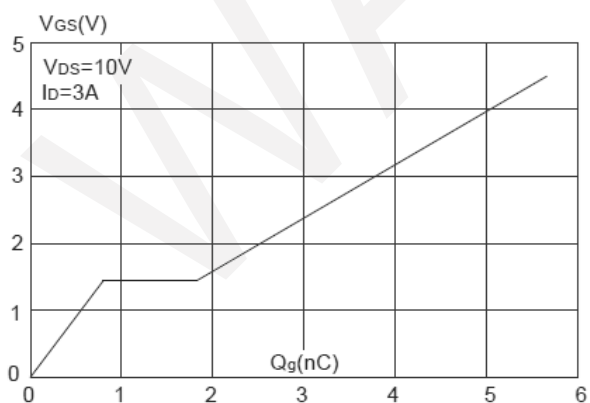
Typical Transfer Characteristics



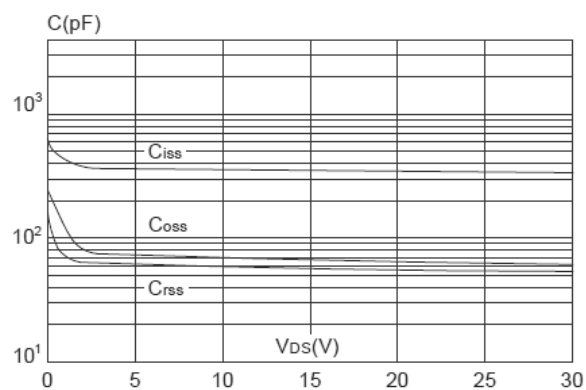
On-resistance vs. Drain Current



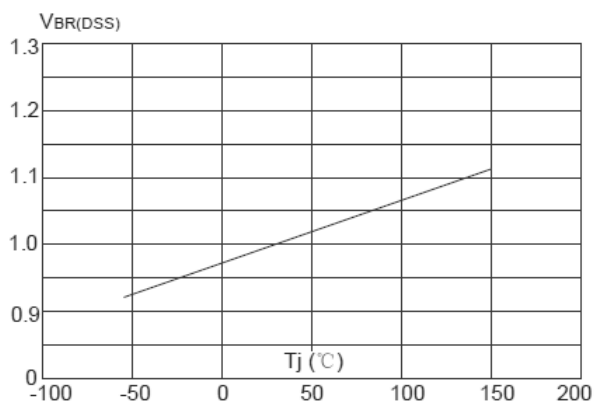
Body Diode Characteristics



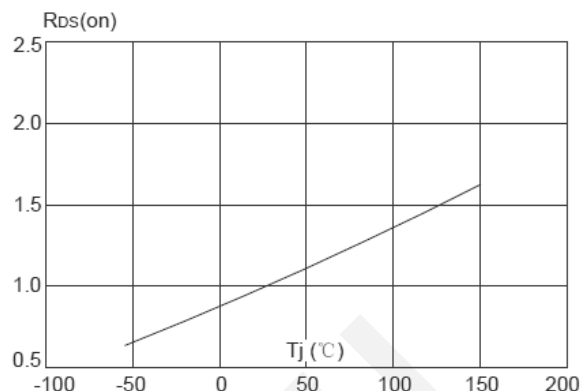
Gate Charge Characteristics



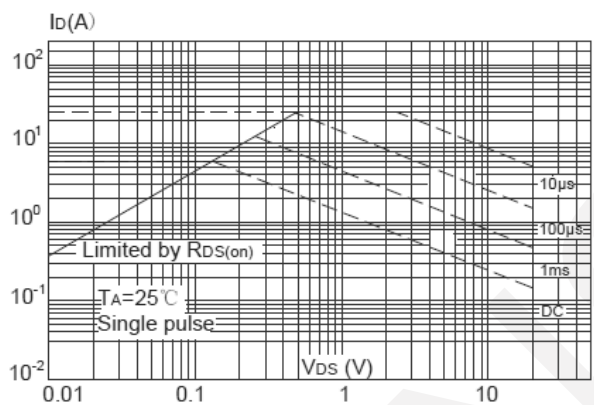
Capacitance Characteristics



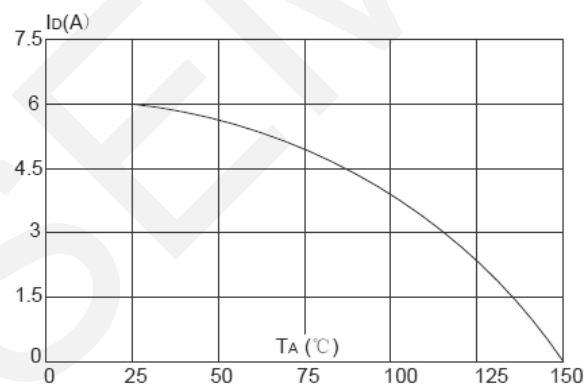
Normalized Breakdown Voltage vs. Junction Temperature



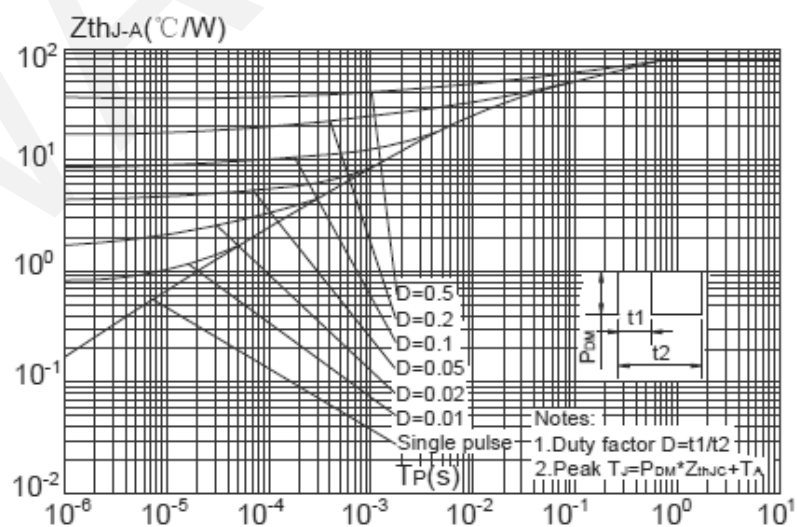
Normalized on Resistance vs. Junction Temperature



Maximum Safe Operating Area

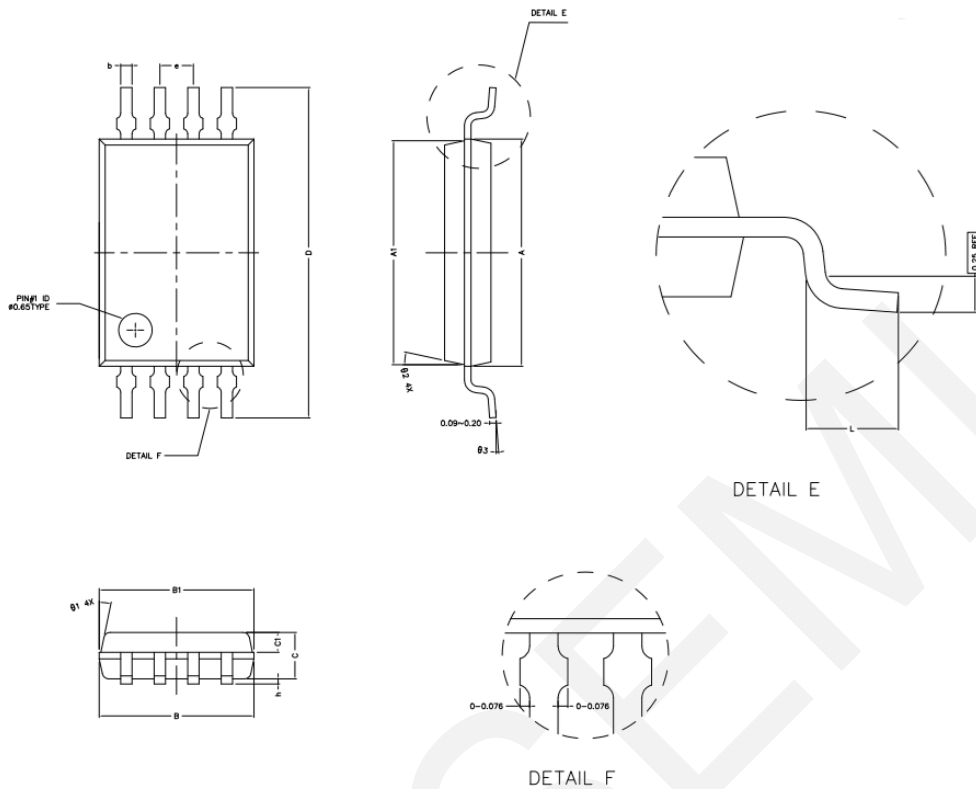


Maximum Continuous Drain Current vs. Ambient Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

7.Package Dimensions



COMMON DIMENSIONS (UNITS OF MEASURE IS mm)			
	MIN	NORMAL	MAX
A	4.300	4.400	4.500
A1	4.240	4.340	4.440
B	3.050	3.150	3.250
B1	2.840	2.940	3.040
C	0.850	0.900	0.950
C1	0.337	0.387	0.437
D	6.250	6.400	6.550
L	0.450	0.600	0.750
b	0.170	0.220	0.300
h	0.050	0.100	0.150
e	0.650TYPE		
θ ₁	12° TYPE		
θ ₂	12° TYPE		
θ ₃	0° ~ 7°		

7.Important Notice

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